

IPC-4101 /40 /41 UL - File Number E41625

Isola offers a product line of polyimide-based prepreg (P25) and core material (P95) for high temperature printed circuit applications.

PRODUCT FEATURES

Industry Recognition

- UL File Number: E41625
- RoHS Compliant

Performance Attributes

- Lead-free assembly compatible
- 6x 260°C reflow capable

Processing Advantages

- Via filling capability
- Multiple reflow capable
- Multiple lamination cycles

PRODUCT AVAILABILITY

Standard Material Offering: Laminate

- 2 to 125 mil (0.05 to 3.2 mm)

Copper Foil Type

- HTE Grade 3

Copper Weight

- ½ to 3 oz (18 to 105 µm) available
- Thinner copper foil available

Standard Material Offering: Prepreg

- Tooling of prepreg panels
- Moisture barrier packaging

Glass Fabric Availability

- E-glass

These products consist of an HB flammability rated polyimide resin system suitable for military, commercial or industrial electronic applications requiring superior performance and the utmost in thermal properties. These products utilize a polyimide and thermoplastic blend resin, fully cured without the use of MDA (Methylenedianiline). This results in a polymer with a high Tg without the characteristic difficulties of brittleness and low initial bond strength associated with traditional thermoset polyimides.

PRODUCT ATTRIBUTES



HIGH THERMAL
RELIABILITY



HIGH
TEMPERATURE

TYPICAL MARKET APPLICATIONS



AUTOMOTIVE &
TRANSPORTATION



AEROSPACE
& DEFENSE

ORDERING INFORMATION:

Contact your local sales representative or contact info@isola-group.com for further information.

Isola Group

6565 West Frye Road Chandler,
AZ 85226 Phone: 480-893-6527
Fax: 480-893-1409

Isola Asia Pacific

(Hong Kong) Ltd. 12/F,
Kin Sang Commercial Centre,
49 King Yip Street, Kwun Tong,
Kowloon,
Hong Kong Phone: 852-2418-1318
Fax: 852-2418-1533

Isola GmbH

Isola Strasse 2 D-52348 Düren,
Germany Phone: 49-2421-8080
Fax: 49-2421-808164

Typical Values Table

Property		Typical Value	Units	Test Method
			Metric (English)	IPC-TM-650 (or as noted)
Glass Transition Temperature (Tg) by DSC		260	°C	2.4.25C
Decomposition Temperature (Td) by TGA @ 5% weight loss		416	°C	2.4.24.6
Time to Delaminate by TMA (Copper removed)	A. T260 B. T288	60	Minutes	2.4.24.1
Z-Axis CTE	A. Pre-Tg B. 50 to 260°C, (Total Expansion)	55 1.5	ppm/°C %	2.4.24C
X/Y-Axis CTE	Pre-Tg	13/14	ppm/°C	2.4.24C
Thermal Conductivity		0.4	W/m·K	ASTM E1952
Thermal Stress 10 sec @ 288°C (550.4°F)	A. Unetched B. Etched	Pass	Pass Visual	2.4.13.1
Dk, Permittivity	A. @ 100 MHz	3.83	—	2.5.5.9
	B. @ 500 MHz	3.80		2.5.5.9
	C. @ 1 GHz	3.78		2.5.5.9
	D. @ 2 GHz	3.76		Bereskin Stripline
	E. @ 5 GHz	3.73		Bereskin Stripline
	F. @ 10 GHz	3.73		Bereskin Stripline
Df, Loss Tangent	A. @ 100 MHz	0.0135	—	2.5.5.9
	B. @ 500 MHz	0.0151		2.5.5.9
	C. @ 1 GHz	0.0172		2.5.5.9
	D. @ 2 GHz	0.0179		Bereskin Stripline
	E. @ 5 GHz	0.0188		Bereskin Stripline
	F. @ 10 GHz	0.021		Bereskin Stripline
Volume Resistivity	A. After moisture resistance B. At elevated temperature	3.0 x 10 ⁸ 7.0 x 10 ⁸	MΩ-cm	2.5.17.1
Surface Resistivity	A. After moisture resistance B. At elevated temperature	3.0 x 10 ⁶ 2.0 x 10 ⁸	MΩ	2.5.17.1
Dielectric Breakdown		>55	kV	2.5.6B
Arc Resistance		130	Seconds	2.5.1B
Electric Strength (Laminate & laminated prepreg)		44 (1100)	kV/mm (V/mil)	2.5.6.2A
Comparative Tracking Index (CTI)		2 (250-399)	Class (Volts)	UL 746A ASTM D3638
Peel Strength	A. Low profile copper foil and very low profile copper foil all copper foil >17 µm [0.669 mil]	1.14 (6.5)	N/mm (lb/inch)	2.4.8C
	B. Standard profile copper	1.25 (7.0)		2.4.8.2A
	1. After thermal stress	1.25 (7.0)		2.4.8.3
	2. At 125°C (257°F)	1.14 (6.5)		2.4.8.3
Flexural Strength	A. Length direction	456 (66.2)	MPa (kpsi)	2.4.4B
	B. Cross direction	405 (58.7)		
Tensile Strength	A. Length direction	376 (54.5)	MPa (kpsi)	ASTM D3039
	B. Cross direction	249 (36.1)		
Young's Modulus	A. Length direction	3892	ksi	ASTM D790-15e2
	B. Cross direction	3490		
Poisson's Ratio	A. Length direction B. Cross direction	0.187 0.164	—	ASTM D3039
Moisture Absorption		0.5	%	2.6.2.1A
Flammability (Laminate & laminated prepreg)		HB	Rating	UL 94
Relative Thermal Index (RTI)		170	°C	UL 746

NOTES

Visit our site <http://www.isola-group.com> for more details.

Revisions:

A: Initial release - 4/17

B: Corrected units for Flexural and Tensile Strength - 8/18

C: Corrected MOT value to match UL file - 11/18

D: Change MOT to RTI 5/19

E: Corrected Flex Strength. Values reversed 2/23

F: Updated RTI from 140 to 170 per UL rating - 3/24

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